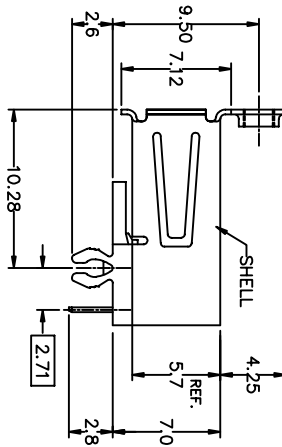
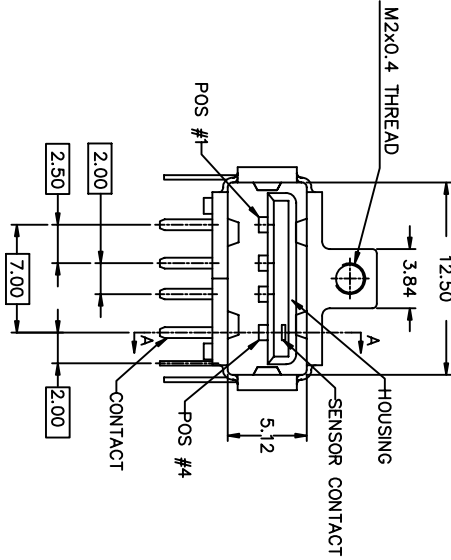
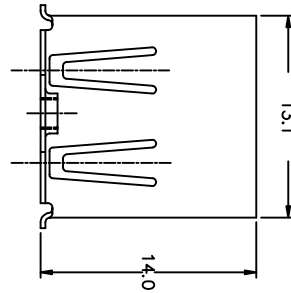
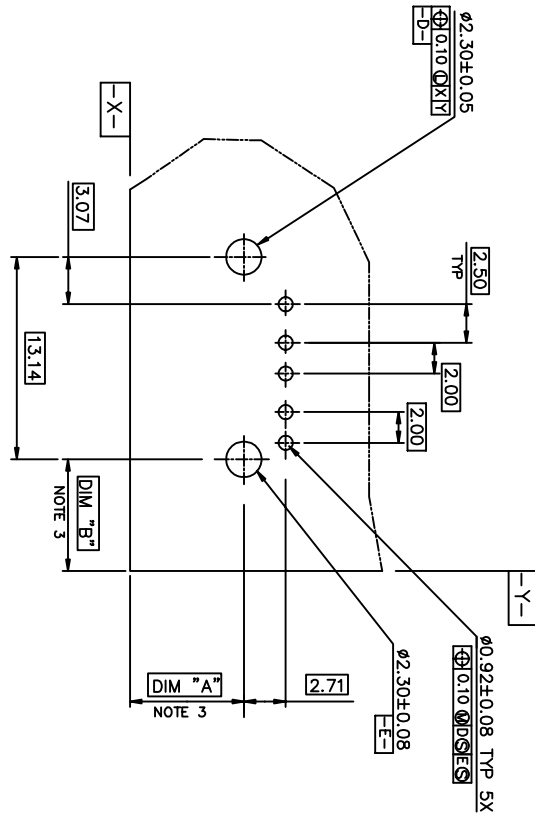


PRODUCT NO.
SEE SHEET 3



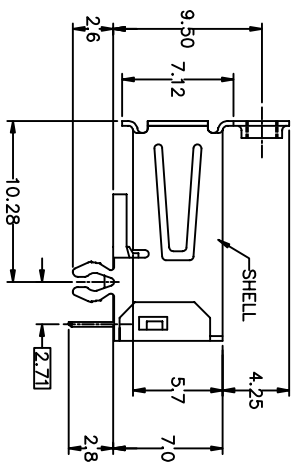
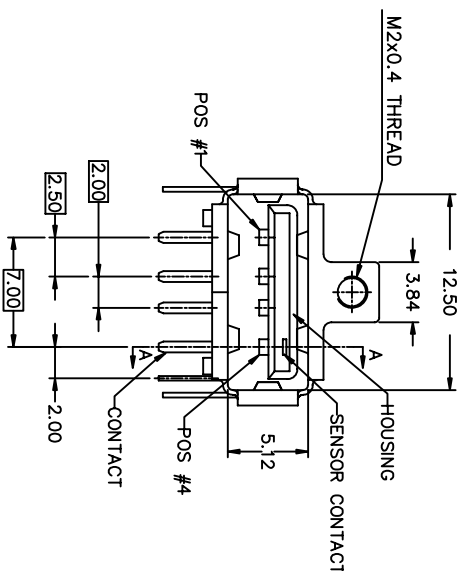
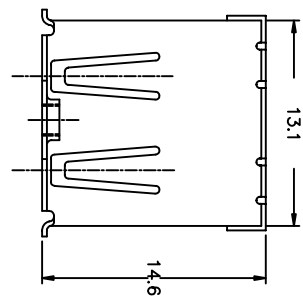
ASSEMBLY WITHOUT BACK SHIELD



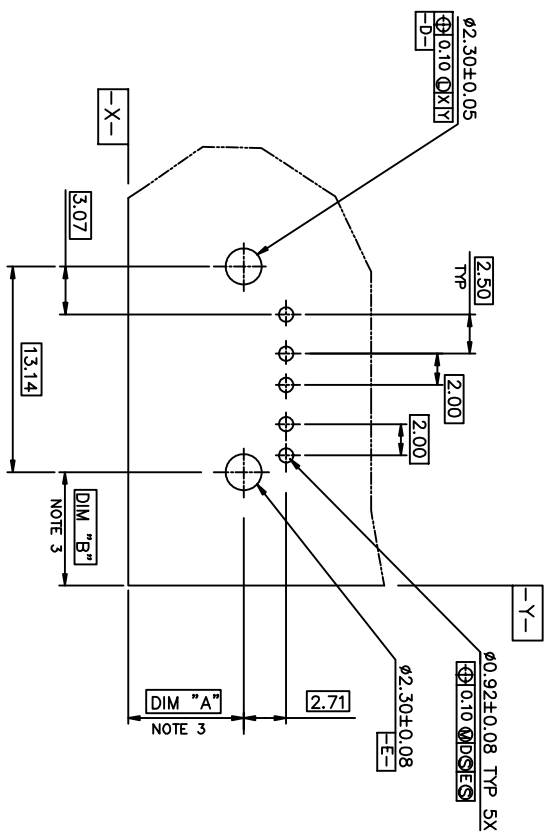
P.C. BOARD LAYOUT

mat'l code	tolerance unless otherwise specified	CUSTOMER COPY	title	product family	dwg no.	code
rev. ecn no. dr. date	linear .00 ± 0.30	projection	UNIV/SERIAL BUS	RECEPIACLE-CATALOG		
A T70233 P P 6/18/97	.000± 0.10	± 3				
B T70333 C L 08/11/97						
C T04-0206 W L 05/13/04						
D N04-0123 PH 12/13/04						
E N06-0101 HB 04/13/06						
sheet revision E B E	chr R Y LUU	01/10/97	scale 2.5:1	A3	61819	sheet 1 of 3
index sheet 1	oppd JENN TSAO 01/10/97					

PRODUCT NO.
SEE SHEET 3



ASSEMBLY WITH BACK SHIELD



P.C. BOARD LAYOUT

mat'l code			tolerance unless otherwise specified			CUSTOMER COPY			BERG ELECTRONICS		
rev.	ecn	no.	dr	date	linear	angular	projection	unit	title	product family	code
B					.00 ± 0.20	± .3°		mm/inch	UNIV/SERIAL BUS S.M.T. RECEPTACLE-CATALOG	61819	2 OF 2
sheet revision			engr			scale			size		
			R Y L U U 01/10/97			2.5:1			A3		
sheet			R Y L U U 01/10/97								
index			00001 JENN TSAO 01/10/97								

PRODUCT NUMBER CODE

$$\frac{61819}{-} - \frac{X}{-} \frac{X}{-} \frac{X}{-} \frac{X}{-} \frac{S}{-} \frac{LF}{-}$$
BASE PRODUCT NUMBER

HOUSING COLOR OPTIONS

0 -	WHITE
1 -	BLACK

PIN NO. OPTION

0	5	P/N
1	4	P/N

SHELL OPTION

1 - WITHOUT BACK SHIELD
2 - WITH BACK SHIELD

TERMINAL PLATING OPTION

0 - 50u" Ni UNDERPLATE

30u GXI CONIACI AREA
100u" TIN/LEAD TAIL AREA

1 - 50u" NI UNDERPLATE
30u" GYT CONTACT AREA

300 GAL CONTACT AREA
100u" TIN TAIL AREA

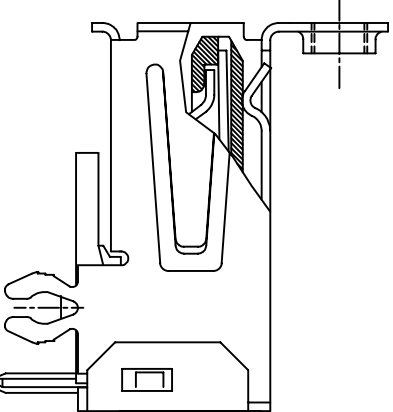
PACKAGING OPTION

B - TUBES

ONLY FOR PANASONIC

LEAD FREE OPTION

WHEN "TERMINAL PLATING OPTION" IS 1



SECTION A-A

- NOTES:
1. MATERIAL:

- CONTACTS: PHOSPHOR BRONZE
SHIELD: PHOSPHOR BRONZE
HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: WHITE
2. PLATING: CONTACTS: GOLD FLASH OVER
PALLADIUM NICKEL (0.76um MINIMUM) IN CONTACT
AREA; 2.54 um TIN-LEAD OR TIN MINIMUM IN SOLDER TAIL AREA.
1.27 um MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
SHIELD: 2.54 um MINIMUM TIN/LEAD OR TIN OVER 1.27 um
MINIMUM NICKEL UNDERPLATE

- ③ DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER.
- ④. RECOMMENDED BOARD THICKNESS IS 0.8~1.2 mm.
- ⑤ MAXIMUM PANEL THICKNESS TO BE 2.67 mm IF MOUNTED BEHIND PANEL.

6. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
7. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008
8. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONNECTION, INFRO-RED OR VAPOR PHASE REFLOW OVEN.

[illegible]